

the heat sink plate has concavo-convex portions formed on an exposed surface thereof and is disposed so as to be opposed to a main surface on which semiconductor elements of the semiconductor chip are formed; and

the heat sink plate is so formed that the convex portions do not protrude from the surface of the sealing member to the outside.

7. (Amended) A semiconductor device, comprising:

- a substrate;
- a semiconductor chip mounted on the substrate;
- external electrodes provided on the back of the substrate, for connecting electrodes of the semiconductor chip to the outside;
- a sealing member for encapsulating the semiconductor chip on the substrate; and
- a heat sink plate fixed by the sealing member, wherein

the heat sink plate has a heat dissipation fin formed integrally therewith, wherein the heat sink plate and the heat dissipation fin have engaging portions brought into engagement with each other, whereby the engaging portions allow detachment of the heat dissipation fin from the heat sink plate.

9. (Amended) The semiconductor device according to claim [8] 7, wherein the engaging portions are respectively formed at the heat sink plate and the heat dissipation fin and comprise a screw and a threaded hole brought into engagement with each other.

12. (Amended) The semiconductor device according to claim [11] 10, wherein the engaging portions are respectively formed at the heat sink plate and the heat dissipation fin and comprise a screw and a threaded hole brought into engagement with each other.

Please cancel claims 2, 4, 6, 8, and 11.

REMARKS

Claims 1, 3, 5, 7 and 9 through 12 are pending in this application. Claims 1, 7, 9 and 12 have been amended and claims 2, 4, 6, 8 and 11 cancelled. Care has been exercised to avoid the introduction of new matter. Applicant notes that claim 7 has been amended by incorporating the limitations of claim 8, and the dependency of claims 9 and 12 appropriately changed. Claim 1 has been clarified by reciting that the heat sink plate is formed so that the convex portions do not protrude from the surface of the sealing member to the outside, adequate descriptive support should for which should be apparent throughout the originally filed disclosure as, for example, Figs. 1 and 2, and the related discussion thereof in the written description of the specification. Applicants submit that the present Amendment does not generate any new matter issue.

A clean copy of amended claims 1, 7, 9 and 12 appears in the Appendix hereto.